

Smart Memory

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Bill Lynch
Sailesh Kumar
and Team

HUAWEI TECHNOLOGIES Co., Ltd.



Overview

- **High Performance Packet Processing Challenges**
- **Solution – Smart Memory**
- **Smart Memory Architecture**

Packet Processing Workload Challenges

- **Sequential memory references**
 - › For lookups (L2, L3, L4, and L7)
 - › Finite automata traversal
- **Read-modify-write**
 - › Statistics, counters, token-bucket, mutex, etc
- **Pointer and link-list management**
 - › Buffer management, packet queues, etc
- **Traditional implementations use**
 - › Commodity memory to store data
 - › NPs and ASICs to process data in memory

**Tons of memory references
and minimal compute**

Performance Barriers:

1. **Memory and chip I/O bandwidth**
2. **Memory latency**
3. **Lock for atomic access**

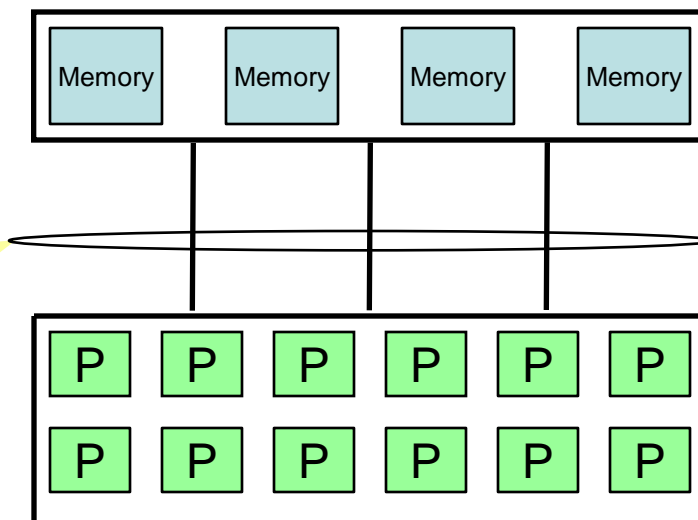
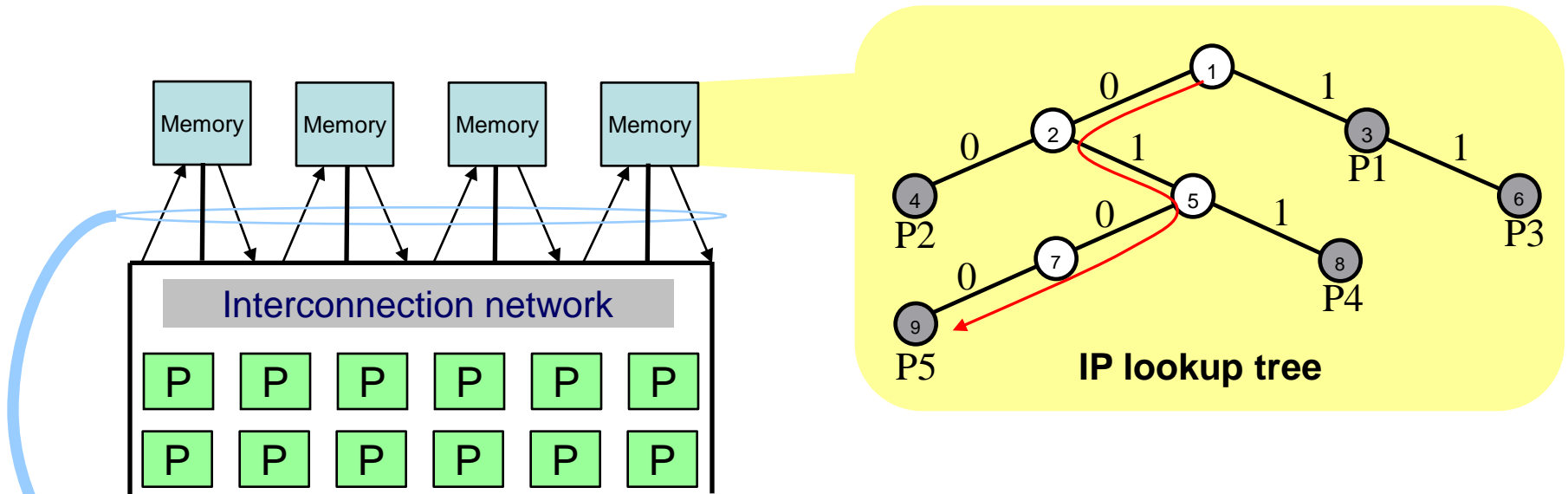


Illustration of Performance Barrier I



Requires several transactions between memory and processors

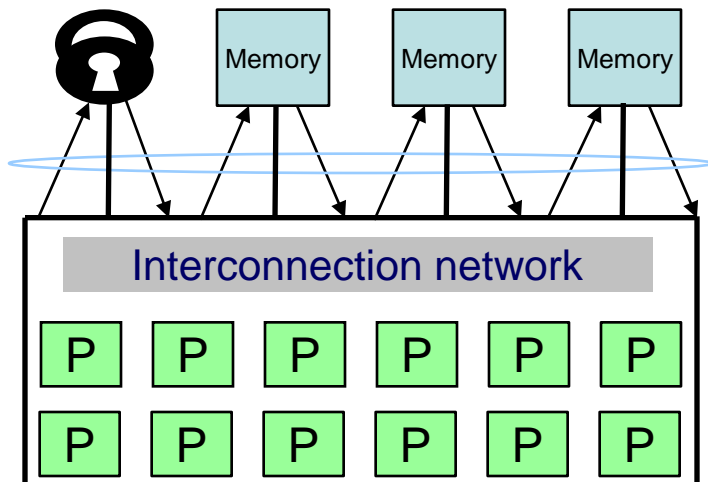
High lookup delay due to high interconnect and memory latency

Low IPC

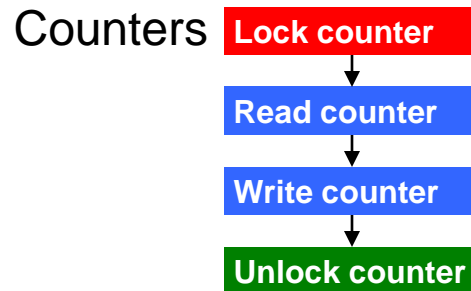
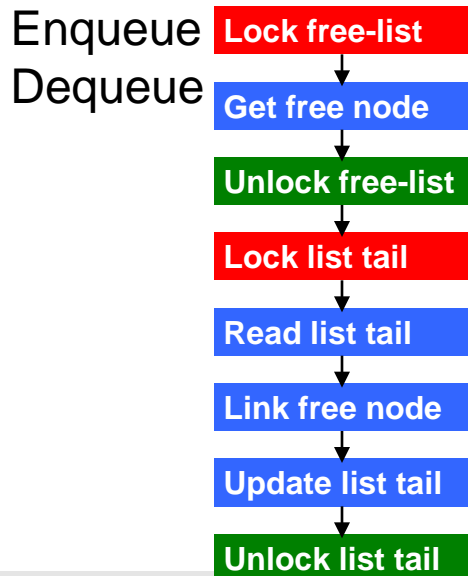
Need more processors

More latency
In interconnect

Illustration of Performance Barrier II



- Lookups are read-only so relatively easy
- Link-list, counters, policers, etc are **read-modify-write**
- Requires per memory address **lock** in multi-core systems



Locks often kept in memory

Requires another transaction

Adds significant latency

Single queue or single counter operations are **extremely slow**

Overview

✓ High Performance Packet Processing Challenges

- › Memory bandwidth and latency
- › Limited I/O bandwidth

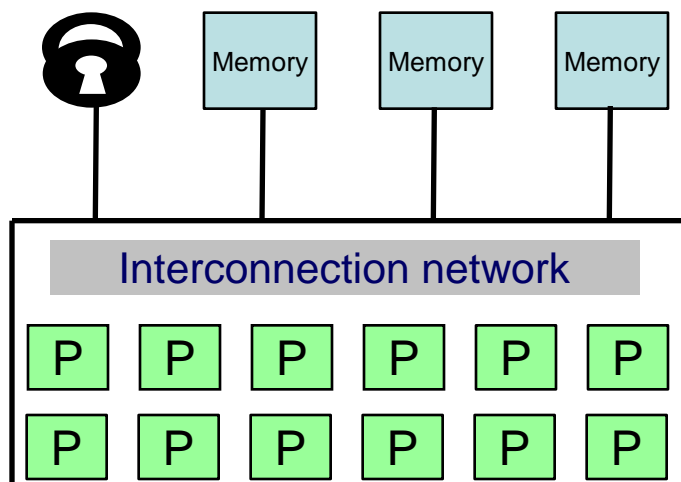
● Solution – Smart Memory

- › Attach simple compute with data
- › Attach lock with data
- › Enable local memory communication

● Smart Memory Architecture

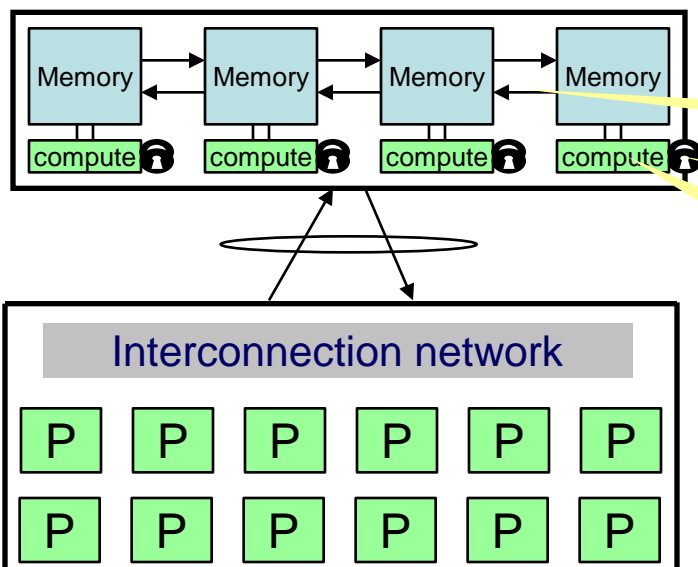
- › Hybrid memory – eDRAM + DDR3-DRAM
- › Serial I/O

Introduction to Smart Memory



- **What is the real problem?**
 - › Compute occurs far away from data
 - › Lock acquire/release occurs far from data

Fortunately, compute for packet processing jobs are very modest!



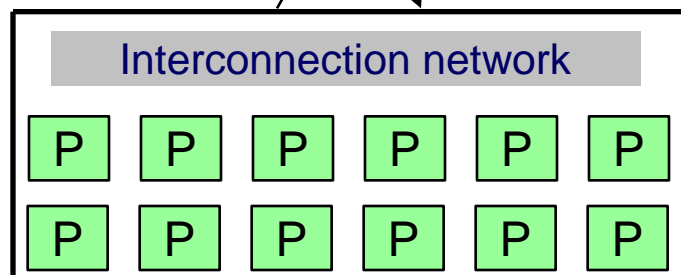
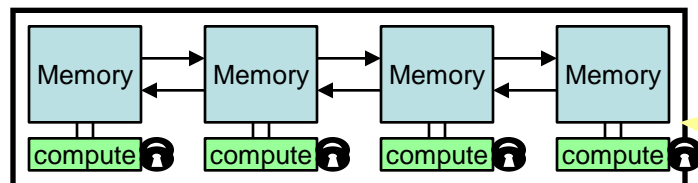
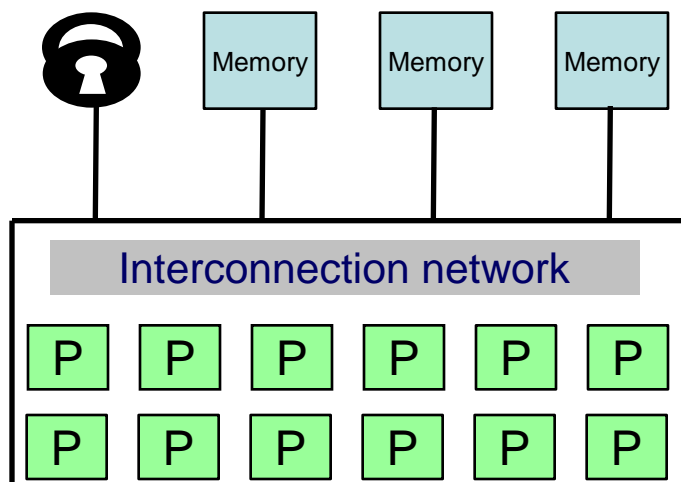
- **Solution: Make memory smarter by:**

Enabling local communication

Managing lock close to data

Keeping compute close to data

Introduction to Smart Memory



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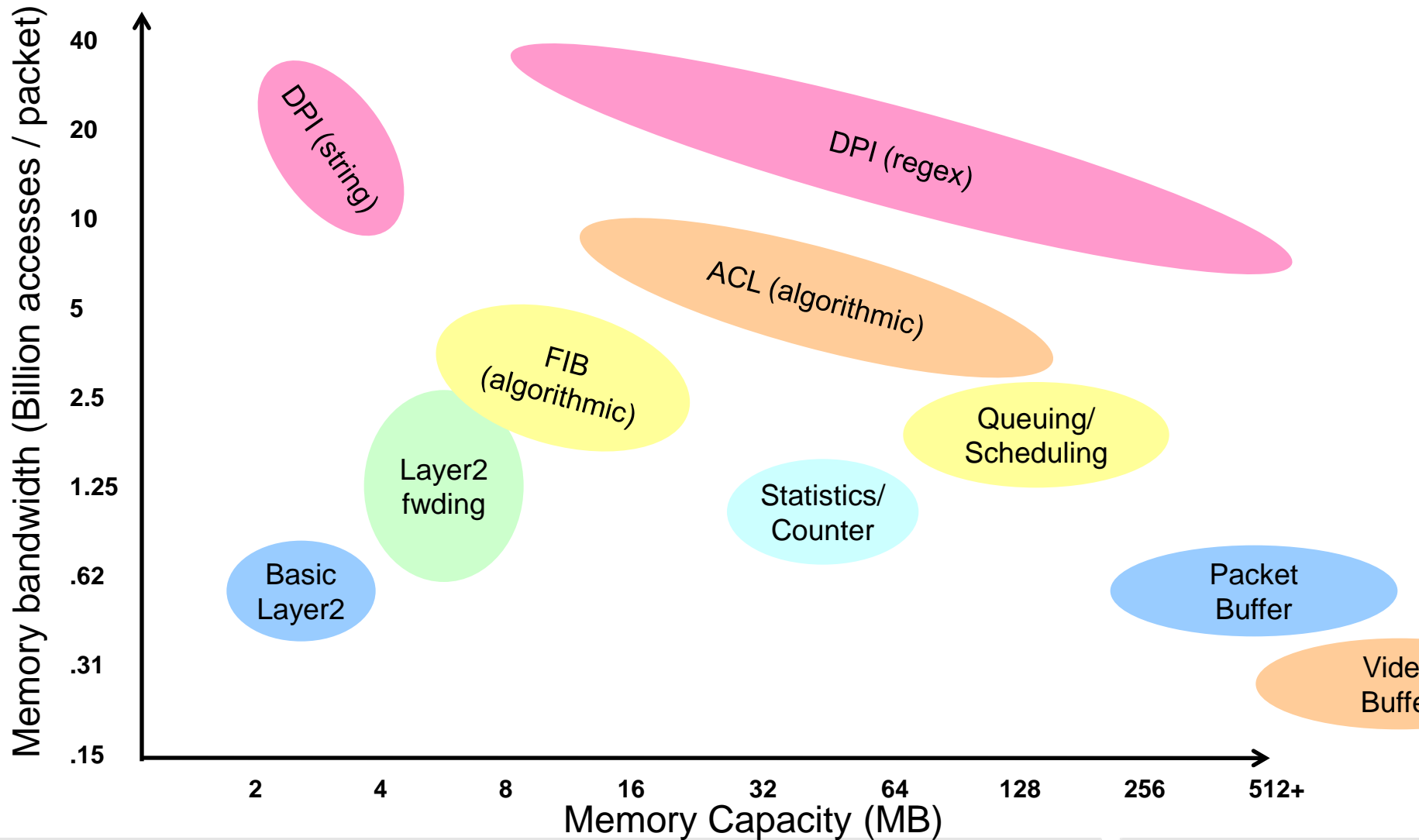
Smart Memory Advantages (Get more off fewer transactions!)

1. Lower I/O bandwidth
2. Lower processing latency
3. Higher IPC
4. Significantly higher single counter/queue performance

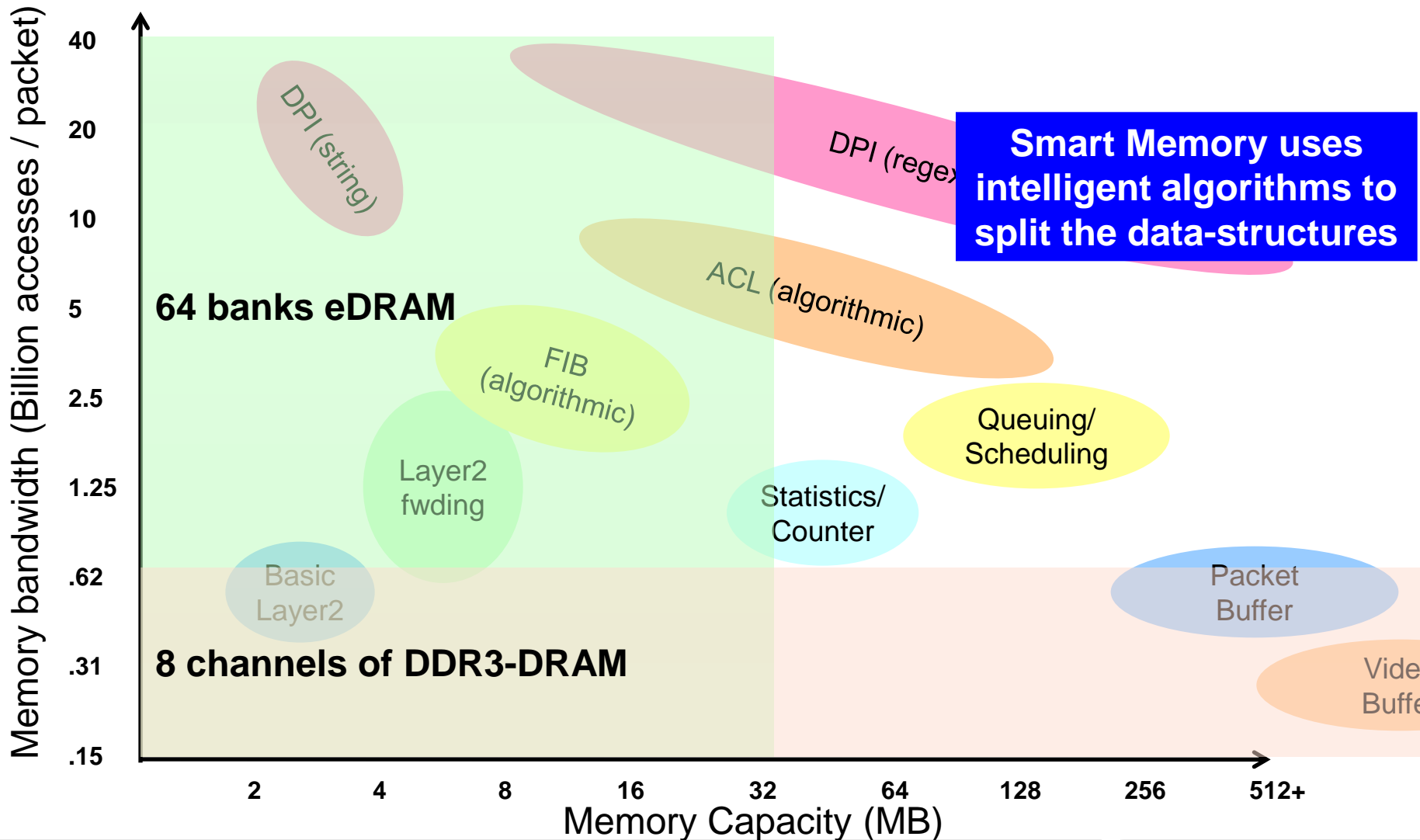
Overview

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 - › Limited I/O bandwidth
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- **Smart Memory Architecture**
 - › Hybrid memory – eDRAM + DDR3-DRAM
 - › Serial chip I/O

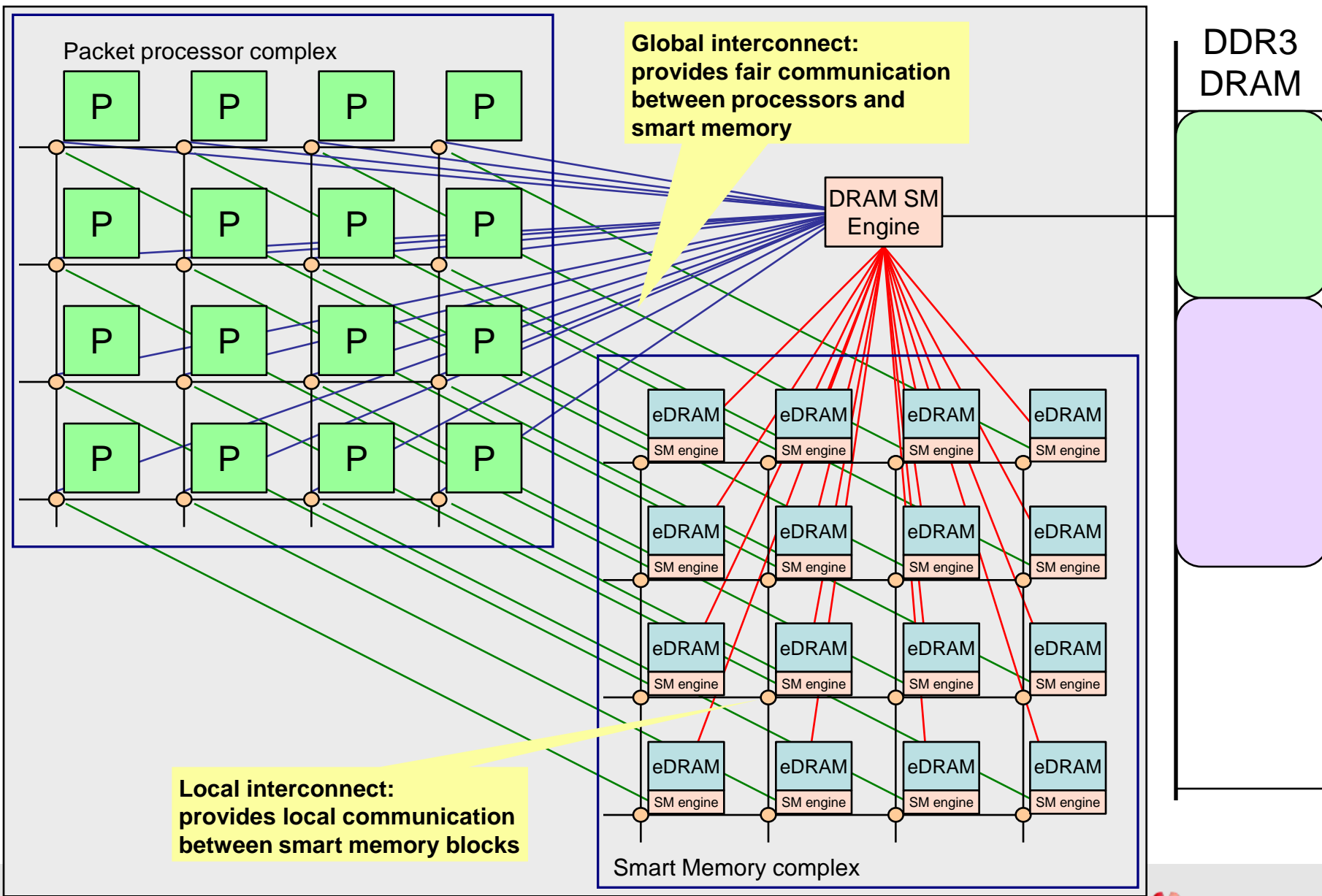
Smart Memory Capacity and Bandwidth @100G



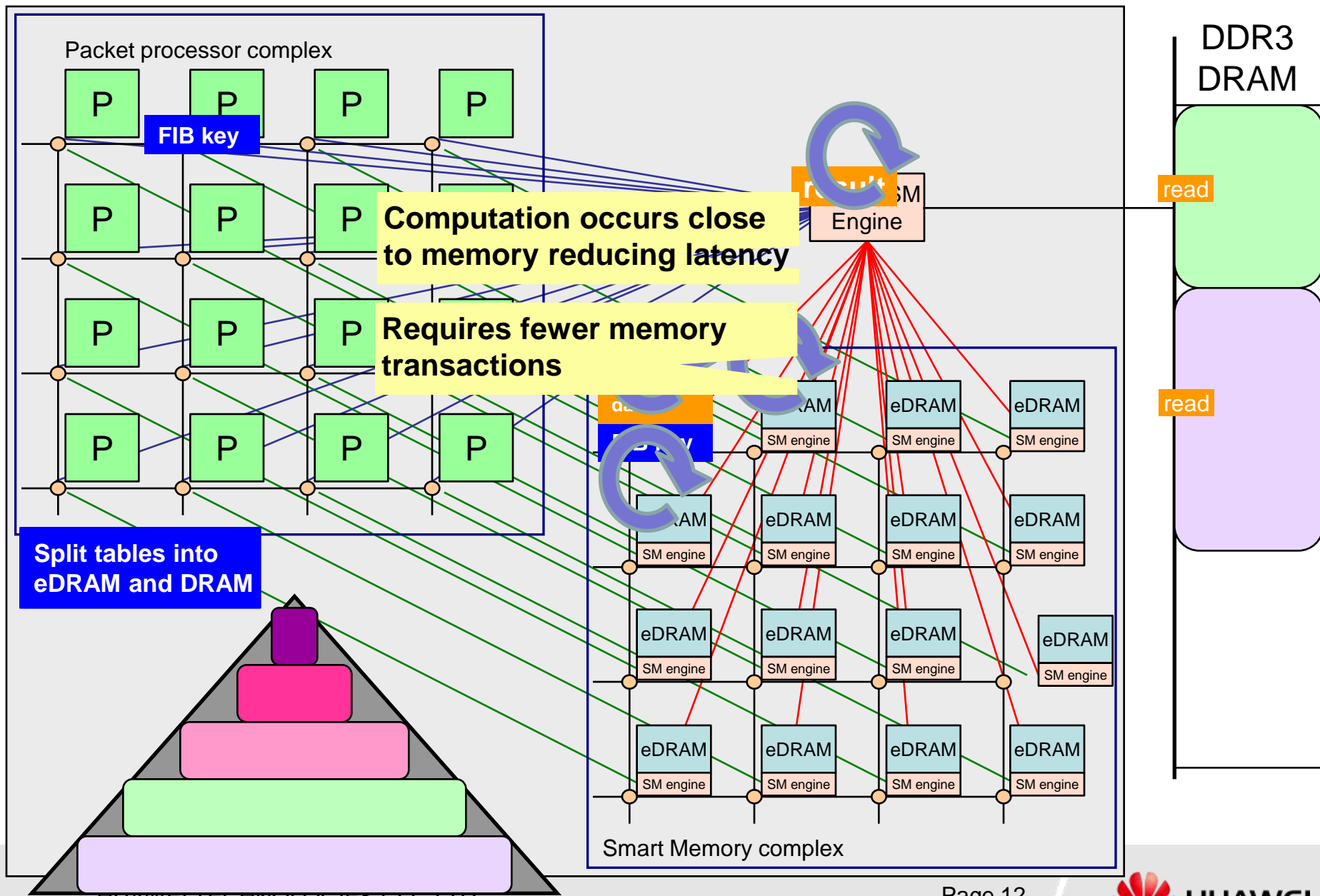
Smart Memory Capacity and Bandwidth @100G



Smart Memory High Level Architecture

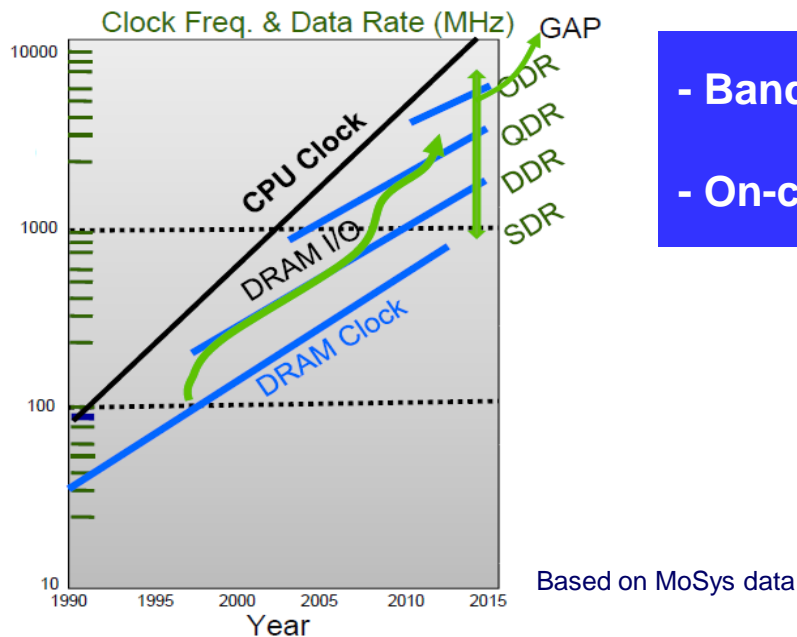


Smart Memory High Level Architecture



I/O Technology Choice in Smart Memory

- Smart Memory reduces the chip I/O bandwidth significantly
- How to further optimize it?



- Bandwidth, latency and I/O bandwidth gap is growing
- On-chip bandwidth is much higher than memory I/O

Smart Memory use serial I/O

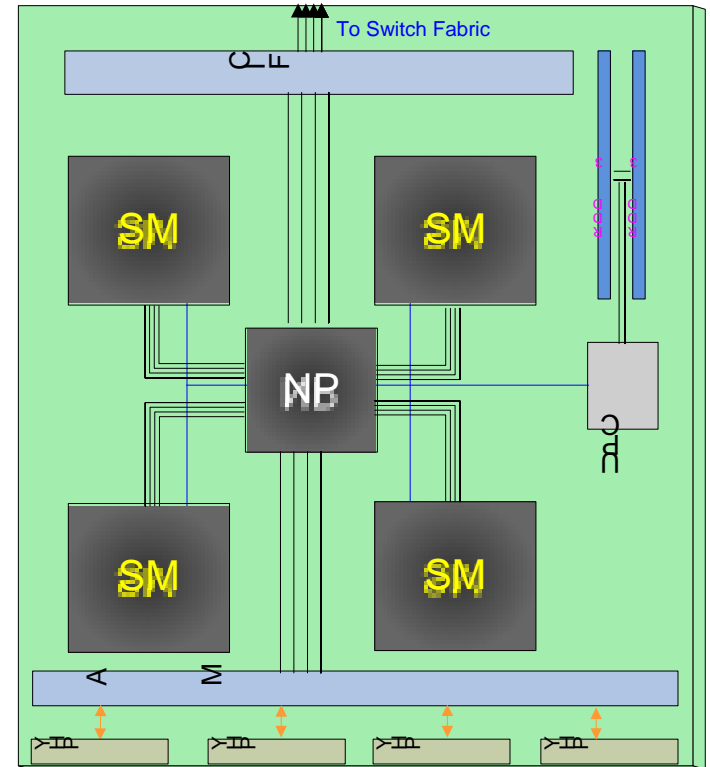
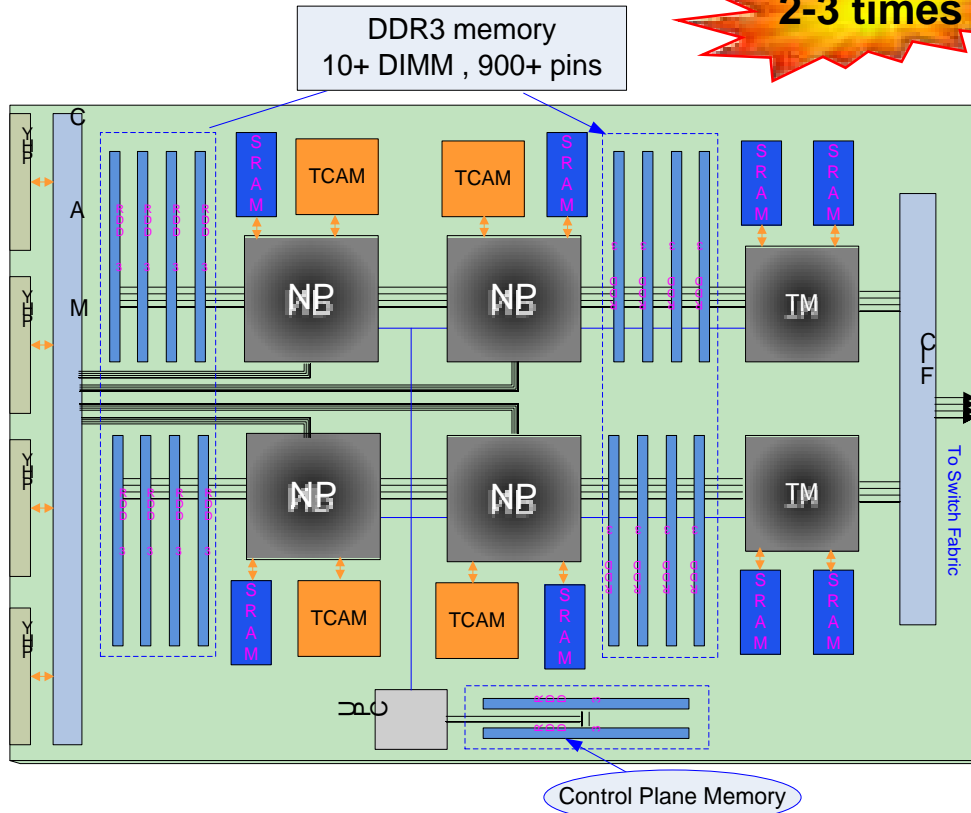
- 4X throughput than RLDRAM and QDR
- 3X fewer pins than DDR3 and DDR4
- 2.5X reduces I/O power

High Speed Line Card with Smart Memory

540+ w	Power	212- w
472+ cm ²	Area	148 cm ²
5600+ \$	Cost	2520 \$

Traditional Line Card

Line Card with SM



Concluding Remarks

- **Packet Processing Bottlenecks**

- › Data away from compute
- › I/O and memory bandwidth

- **Smart Memory**

- › Keep compute close to data
- › Keep locking close to data
- › Provide inter-memory connect

- **Advantages**

- › Reduced chip I/O bandwidth
- › High performance and low latency
- › Feature rich, flexible and programmable
- › Lower cost
- › One chip for several functions

Thank You

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